

# Sandia National Laboratories

## Option 1: Qubits in Gate-Defined Silicon Quantum Dots

### Charge Noise Assessment Platform

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#### What can fabrication do to improve charge noise in Si-based qubits?

- What parameters most influence charge noise?
- What are the metrics?
  - Absolute charge noise level
  - Deviations in charge noise

#### How can we assess charge noise improvements?

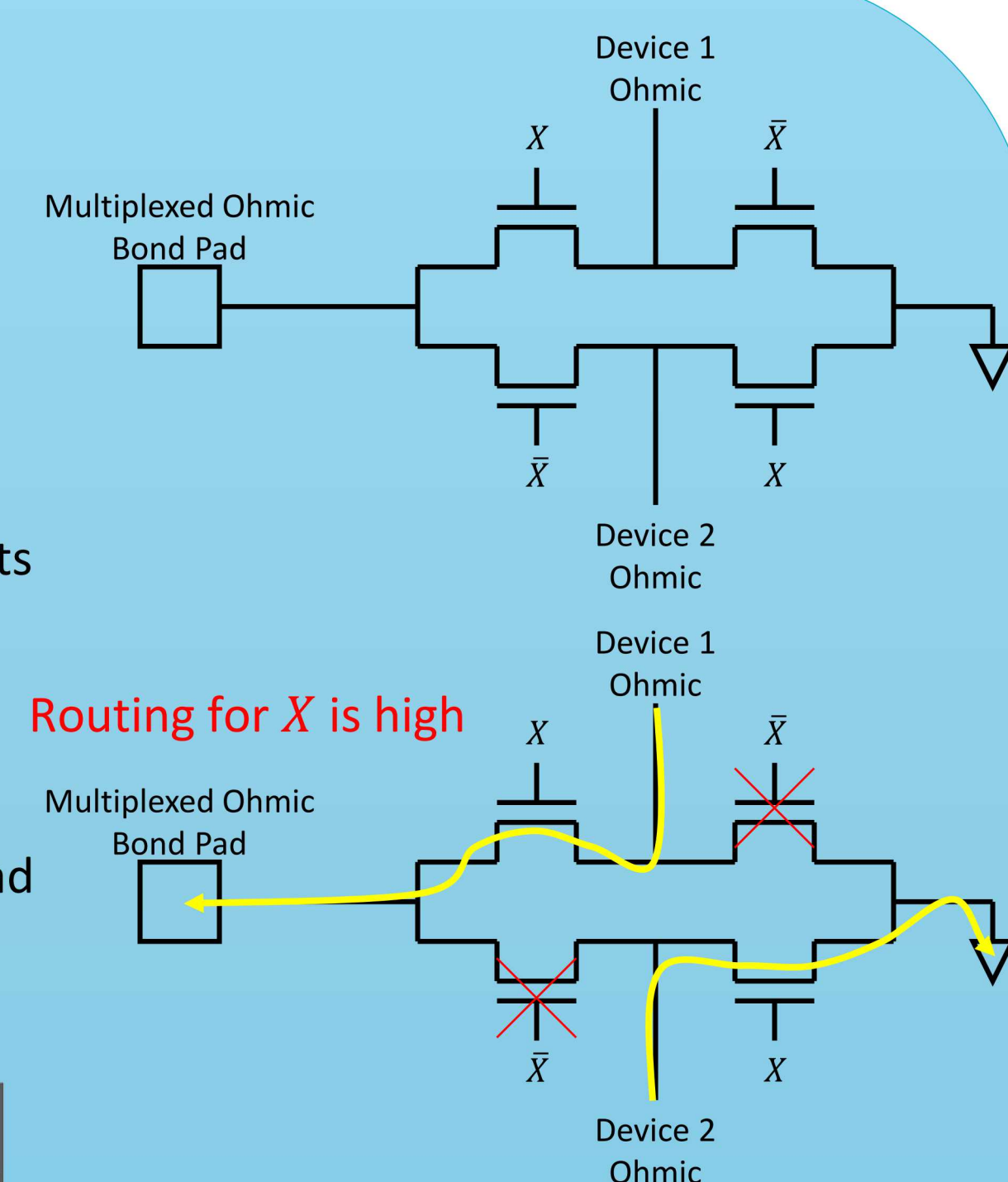
- Need statistics – measure lots of devices
- Need fast measurement of multiple devices
- Maximize throughput of devices assuming a single cool down
- “Simple” devices – Double QD with SET

#### Throughput increases:

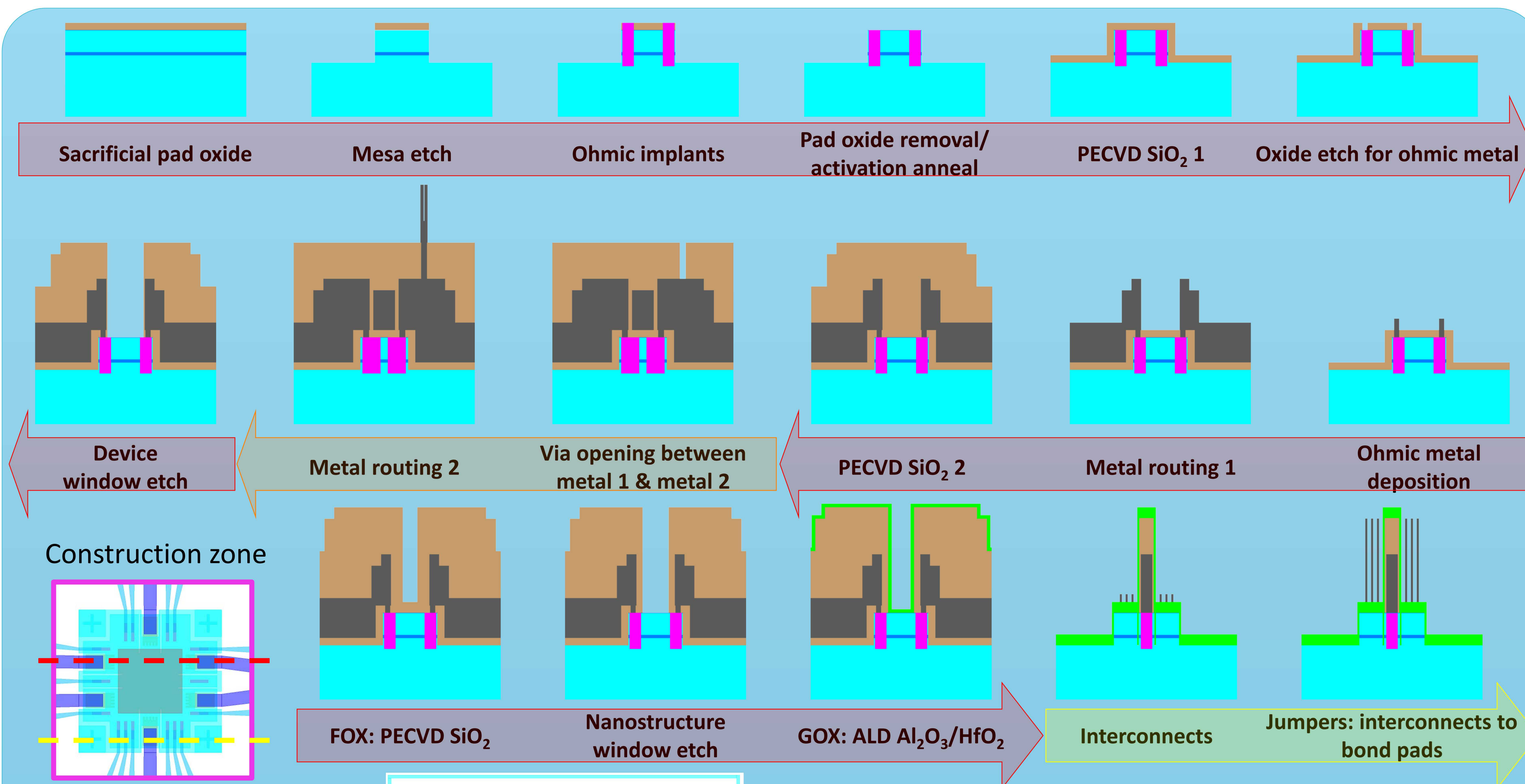
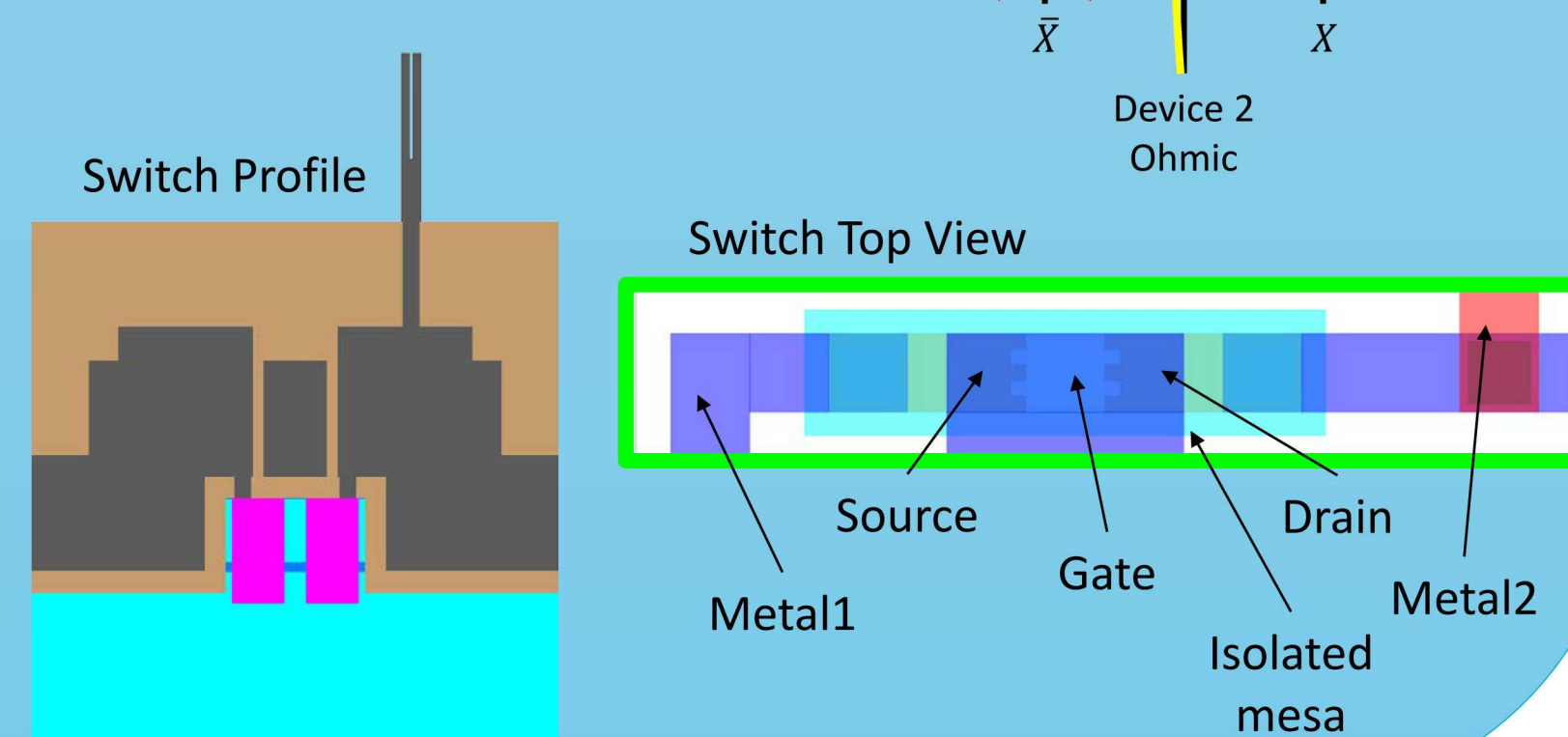
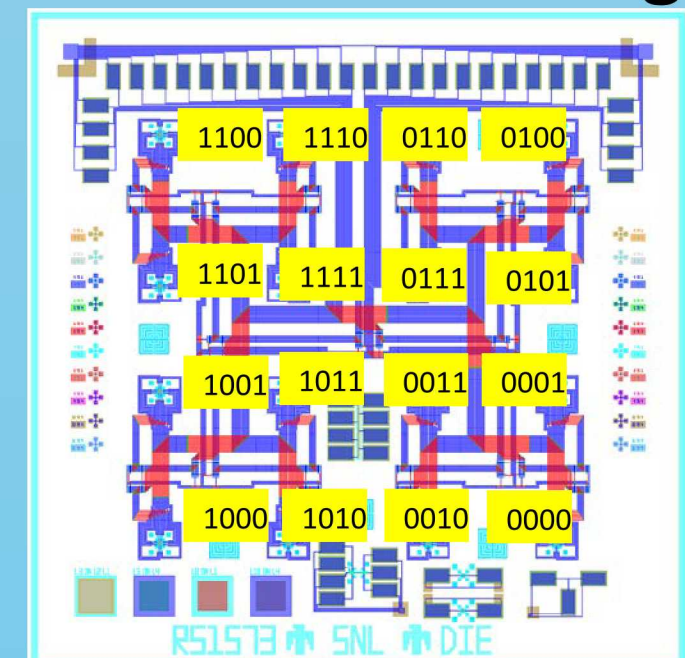
- Multiple devices per die - Quickly run out of control lines
- Multiplexing
  - Shared gate connections
  - Ohmics are multiplexed with on-chip switches
  - For DQD+SET requires  $22+2*n$  connections for  $2^n$  devices
  - 16 devices ( $n=4$ ) requires 30 connections → 32 charge noise measurements!

#### Multiplexing Setup

- Multiplexing greatly reduces number of connections needed
- Our design requires  $2*n$  connections
  - Providing digital signal line ( $X$ ) and its complement ( $\bar{X}$ )
- On-chip inverter is impractical
  - NMOS only without additional implants
  - NMOS inverters require large power dissipation
- Critical that devices not under measurement be grounded
  - Device on → ohmic routed to bond pad
  - Device off → ohmic routed to ground
- Each ohmic requires two switches per split



#### Device Addressing



#### Future Work

- Add nanostructures
  - Start with Hall bars to assess mobility across a die
    - Validate switch performance
    - Move on to DQD
      - Improve yield by patterning fewer devices per die
      - 4, 8, and 16 DQD structure per die
- Assess charge noise for  $\text{Al}_2\text{O}_3$  and  $\text{HfO}_2$  gate dielectrics
- Dive deeper into impacts of other fabrication parameters
  - Gate materials, dielectric deposition temperatures, etc.



#### MESA complex:

Class 1 Si cleanroom (CMOS)  
 Class 10 Mixed materials (III-V R&D)

#### Capabilities:

Up to 8" wafer processing, novel integration, small volume production.



#### CINT complex:

Class 100 cleanroom

#### Capabilities:

Up to 4" wafer processing, user facility for visiting collaborators.

Special thanks to Lisa Edge for providing SiGe wafers